

Title (en)

Process for electrochemical dissolution of high-melting point special alloy powders and electrolytic cell suitable therefor

Title (de)

Verfahren zur elektrochemischen Auflösung von Pulvern aus hochschmelzenden Sonderlegierungen und dafür geeignete Elektrolysezelle

Title (fr)

Procédé de dissolution électrochimique de poudres d'alliages spéciaux à point de fusion élevé et cellule d'électrolyse à cet effet

Publication

EP 1354968 B1 20090708 (DE)

Application

EP 03007731 A 20030404

Priority

DE 10216944 A 20020417

Abstract (en)

[origin: EP1354968A2] Process for electrochemically digesting powdered precursors comprises introducing a powder charge between two liquid-permeable electrodes of an electrolysis cell. The powder charge flows from the electrolyte vertically to the electrode surfaces. An Independent claim is also included for an electrolysis cell.

IPC 8 full level

C22B 7/00 (2006.01); **C25B 11/03** (2006.01); **C22B 3/02** (2006.01); **C22B 3/04** (2006.01); **C22B 34/00** (2006.01); **C22B 34/36** (2006.01); **C25B 1/00** (2006.01); **C25C 5/00** (2006.01); **C25C 5/02** (2006.01); **C25C 7/00** (2006.01); **C25C 7/02** (2006.01); **C25D 15/00** (2006.01)

CPC (source: EP KR US)

C22B 3/045 (2013.01 - EP US); **C22B 7/006** (2013.01 - EP US); **C22B 11/042** (2013.01 - EP US); **C22B 34/36** (2013.01 - EP US); **C25C 5/02** (2013.01 - KR); **Y02P 10/20** (2015.11 - EP US)

Citation (examination)

SU 1057432 A1 19831130 - V PT I ELEKTROBYTOVYM MASHINAM [SU]

Cited by

EP2081685A4; US9023129B2; WO2011074948A1

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DOCDB simple family (publication)

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DOCDB simple family (application)

EP 03007731 A 20030404; AT 03007731 T 20030404; CA 2425504 A 20030414; CN 03123122 A 20030417; DE 10216944 A 20020417; DE 50311678 T 20030404; DK 03007731 T 20030404; ES 03007731 T 20030404; JP 2003111884 A 20030416; KR 20030023871 A 20030416; MX PA03003341 A 20030415; PE 2003000385 A 20030416; PT 03007731 T 20030404; RU 2003110981 A 20030417; SI 200331651 T 20030404; TW 92108750 A 20030416; US 41395803 A 20030415; US 55829506 A 20061109